What is claimed is:

1. A thermosetting resin sheet containing an inorganic filler, an epoxy resin and a phenolic resin, and being in a B-stage state with a projected area of 1766331400 mm^2 or more as viewed in a plan view.

~~2. The thermosetting resin sheet according to claim 1,~~

wherein

an elastic modulus before heat curing is 2.51.5 × 10^3 Pa or more and 3 × 10^{34} Pa or less in a temperature range of 90°C to 130°C, and

a content of the inorganic filler is 80 to 90% by weight (excluding 80% by weight).

32. The thermosetting resin sheet according to claim 1 ~~or 2~~, wherein an average particle size of the inorganic filler is 54 μm or less.

~~4. The thermosetting resin sheet according to any one of claims 1 to 3, wherein a content of the inorganic filler is 70 wt% or more and 95 wt% or less.~~

53. The thermosetting resin sheet according to ~~any one of~~ claims 1 or~~to~~ 24, containing an elastomer~~, an epoxy resin, and a phenolic resin~~.

~~6~~4. A thermosetting resin sheet wound body formed by winding a long body of the thermosetting resin sheet according to any one of claims 1 to ~~5~~3 in a roll form.

~~7~~5. A method for manufacturing an electronic component package, comprising:

a laminating step of laminating the thermosetting resin sheet according to any one of claims 1 to ~~5~~3 onto one or plural electronic components so as to cover the one or plural electronic components; and

a sealed body forming step of forming a sealed body by heat-curing the thermosetting resin sheet,

wherein a ratio of a projected area of the electronic component as viewed in a plan view relative to a projected area of the thermosetting resin sheet as viewed in a plan view is 50% or more.

~~8~~6. The method for manufacturing an electronic component package according to claim ~~7~~5, wherein the laminating step is carried out by a thermal pressing process.

~~9~~7. The method for manufacturing an electronic component package according to claim ~~7~~5 or ~~8~~6, further comprising a dicing step of forming an electronic component module by dicing the sealed body.

~~10~~8. The method for manufacturing an electronic component package according to any one of claims ~~7~~5 to ~~9~~7,

wherein the electronic component is a semiconductor chip or a semiconductor wafer.